

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of )  
 )  
Yamazaki et al. )  
 )  
Serial No.: )  
 )  
Filed: )  
 )  
For: Semiconductor Device And )  
Manufacturing Method Thereof )  
 )  
Art Unit: )  
 )  
Examiner: )

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:  
Commissioner for Patents ,  
P.O. Box 1450, Alexandria, VA 22313-1450 on

August 18, 2003

(Date of Deposit)

Shannon Wallace

Name of applicant, assignee, or Registered Rep.

Shannon Wallace 8/18/03

Signature

Date

Commissioner for Patents  
P.O. Box 1450

August 18, 2003

**PRELIMINARY AMENDMENT A**

Sir:

Prior to examination, please amend the above-identified application as follows:

**IN THE DRAWINGS:**

The attached sheet contains a change to Fig. 6C. This sheet, which includes Figs. 6A-6D, replaces the original sheet including Figs. 6A-6D. Replacement formal drawings for all the figures are also being submitted.